

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- Claim 1. **[Original]** A titanium-copper alloy having high strength and conductivity as a copper alloy comprising:
- three to four percent by mass of Ti,
residual Cu, and
inevitable impurities,
- wherein the area percentage (S(%)) of a Cu-Ti intermetallic compound phase observed in a section perpendicular to the rolling direction is represented by the following formula:
- $$S(\%) \geq 8.1 \times [\text{Ti}] - 17.7$$
- where [Ti] represents the Ti content in percent by mass.
- Claim 2. **[Original]** A titanium-copper alloy according to Claim 1, wherein a conductivity is 16% IACS or more, and 0.2% proof stress is 800 MPa or more.
- Claim 3. **[Withdrawn]** A method of producing a titanium-copper alloy according to Claim 1 or 2 comprising the steps of:
- hot-rolling, cold-rolling, solution-treating, cold-rolling, and aging an ingot,
- wherein a cold working degree prior to the aging is 15% or more, the aging temperature is from 350°C to 450°C, the aging time is from 5 to 20 hours, and the average cooling rate from the aging temperature after the aging to 300°C is 50°C/h or less.